

### General Description

This IGBT is produced using advanced MagnaChip's Field Stop Trench IGBT Technology, which provides low  $V_{CE(SAT)}$ , high switching performance and excellent quality.

This device is for PFC, UPS & Inverter applications.

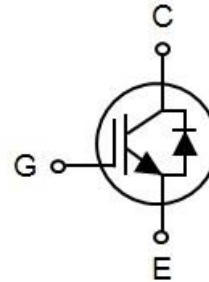
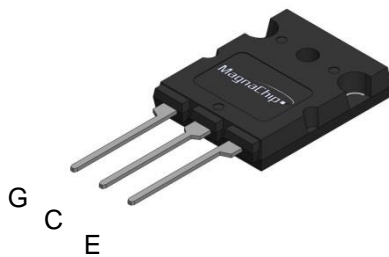
### Applications

- PFC
- UPS
- Inverter

### Features

- High Speed Switching & Low Power Loss
- $V_{CE(sat)} = 2.0V$  @  $I_C = 40A$
- High Input Impedance
- $t_{rr} = 100ns$  (typ.)
- Ultra Soft, fast recovery anti-parallel diode
- Ultra narrowed VF distribution control
- Positive Temperature coefficient for easy paralleling

TO-247



### Absolute Maximum Ratings

Characteristics		Symbol	Rating	Unit
Collector-emitter voltage		$V_{CES}$	1200	V
Gate-emitter voltage		$V_{GES}$	$\pm 20$	V
Collector current	$T_C = 25^\circ C$	$I_C$	80	A
	$T_C = 100^\circ C$		40	A
Pulsed collector current, pulse time limited by $T_{jmax}$		$I_{CM}$	160	A
Diode forward current @ $T_C = 100^\circ C$		$I_F$	40	A
Diode pulsed current, Pulse time limited by $T_{jmax}$		$I_{FM}$	160	A
Power dissipation	$T_C = 25^\circ C$	$P_D$	357	W
	$T_C = 100^\circ C$		142	W
Short circuit withstand time $V_{CE} = 600V$ , $V_{GE} = 15V$ , $T_C = 150^\circ C$ Allowed number of short circuit < 1000 Time between short circuits $\geq 1.0s$		tsc	10	$\mu s$
Operating Junction and storage temperature range		$T_J, T_{stg}$	-55~150	$^\circ C$

### Thermal Characteristics

Characteristics	Symbol	Rating	Unit
Thermal resistance junction-to-ambient	$R_{\theta JA}$	40	$^\circ C/W$
Thermal resistance junction-to-case for IGBT	$R_{\theta JC}$	0.35	
Thermal resistance junction-to-case for Diode	$R_{\theta JC}$	0.8	

## Ordering Information

Part Number	Marking	Temp. Range	Package	Packing	RoHS Status
MBQ40T120FESTH	40T120FES	-55~150°C	TO-247	Tube	Pb Free

## Electrical Characteristics (T<sub>c</sub> =25°C unless otherwise specified)

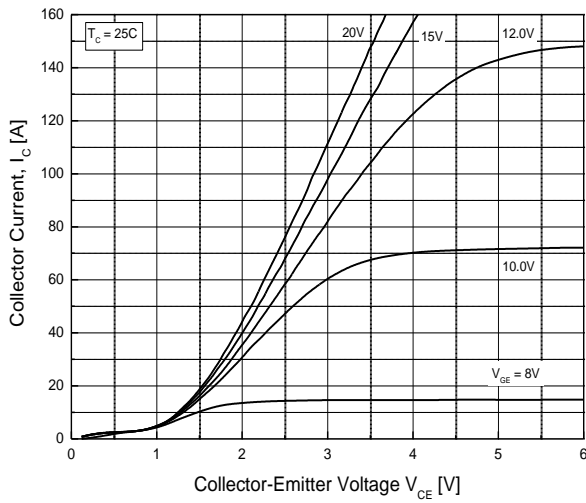
Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Collector-emitter breakdown voltage	BV <sub>CES</sub>	I <sub>C</sub> = 1mA, V <sub>GE</sub> = 0V	1200	-	-	V
Gate-emitter threshold voltage	V <sub>GE(th)</sub>	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 1mA	4.5	5.5	6.5	V
Zero gate voltage collector current	I <sub>CES</sub>	V <sub>CE</sub> = 1200V, V <sub>GE</sub> = 0V	-	-	1	mA
Gate-emitter leakage current	I <sub>GES</sub>	V <sub>GE</sub> = 20V, V <sub>CE</sub> = 0V	-	-	±250	nA
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 40A, V <sub>GE</sub> = 15V, T <sub>C</sub> = 25°C		2.0	2.4	V
		I <sub>C</sub> = 40A, V <sub>GE</sub> = 15V, T <sub>C</sub> = 150°C		2.45		

## Dynamic and Switching Characteristics

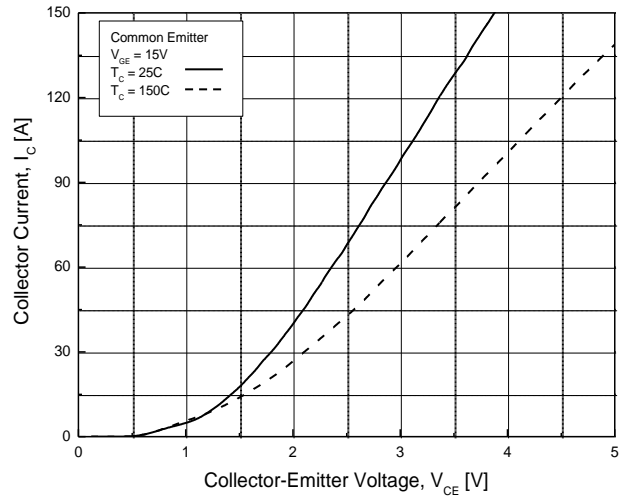
Total gate charge	Q <sub>g</sub>	V <sub>CE</sub> = 600V, I <sub>C</sub> = 40A, V <sub>GE</sub> = 15V	-	341		nC
Gate-emitter charge	Q <sub>ge</sub>		-	52		
Gate-collector charge	Q <sub>gc</sub>		-	126		
Input capacitance	C <sub>ies</sub>	V <sub>CE</sub> = 30V, V <sub>GE</sub> = 0V, f = 1MHz	-	6030	-	pF
Reverse transfer capacitance	C <sub>res</sub>		-	107	-	
Output capacitance	C <sub>oes</sub>		-	206	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>GE</sub> = 15V, V <sub>CC</sub> = 600V, I <sub>C</sub> = 40A, R <sub>G</sub> = 10Ω' Inductive Load, T <sub>C</sub> = 25°C		65		ns
Rise time	t <sub>r</sub>			55		
Turn-off delay time	t <sub>d(off)</sub>			308		
Fall time	t <sub>f</sub>			40		
Turn-on switching energy	E <sub>on</sub>			1.96		mJ
Turn-off switching energy	E <sub>off</sub>			0.54		
Total switching energy	E <sub>ts</sub>			2.50		
Turn-on delay time	t <sub>d(on)</sub>	V <sub>GE</sub> = 15V, V <sub>CC</sub> = 600V, I <sub>C</sub> = 40A, R <sub>G</sub> = 10Ω' Inductive Load, T <sub>C</sub> = 150°C		70		ns
Rise time	t <sub>r</sub>			62		
Turn-off delay time	t <sub>d(off)</sub>			325		
Fall time	t <sub>f</sub>			62		
Turn-on switching energy	E <sub>on</sub>			2.35		mJ
Turn-off switching energy	E <sub>off</sub>			1.61		
Total switching energy	E <sub>ts</sub>			3.96		

## Diode Characteristics (T<sub>c</sub> =25°C unless otherwise specified)

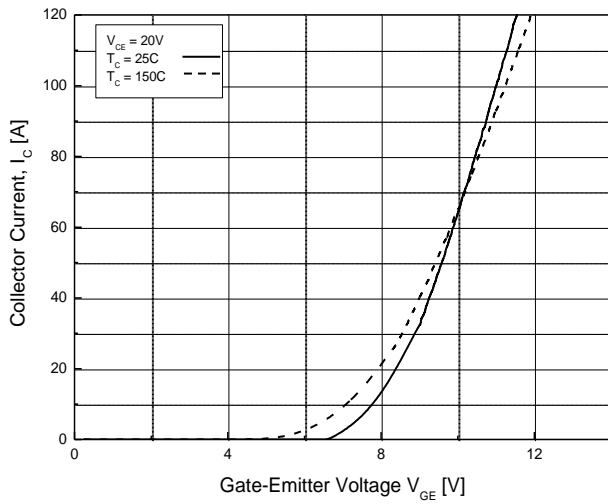
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 40A, T <sub>C</sub> = 25°C	-	2.4	3.0	V
		I <sub>F</sub> = 40A, T <sub>C</sub> = 150°C	-	2.45		
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 40A, di/dt = 200A/ μs, T <sub>C</sub> = 25°C	-	100	-	ns
Reverse recovery current	I <sub>rr</sub>		-	7	-	A
Reverse recovery charge	Q <sub>rr</sub>		-	350	-	nC
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 40A, di/dt = 200A/ μs, T <sub>C</sub> = 150°C	-	180	-	ns
Reverse recovery current	I <sub>rr</sub>		-	10	-	A
Reverse recovery charge	Q <sub>rr</sub>		-	900	-	nC



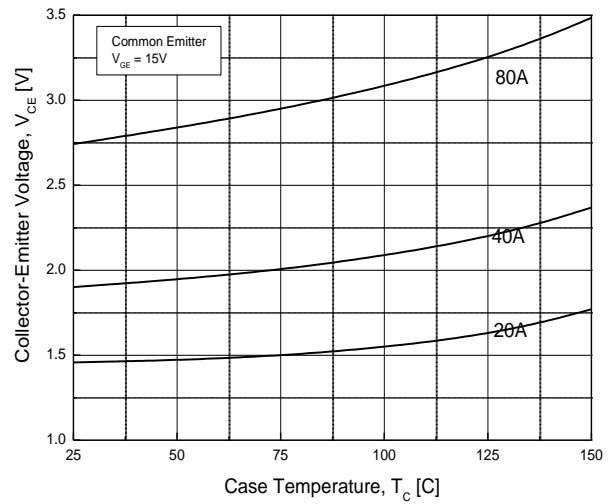
**Fig.1 Typical Output Characteristics**



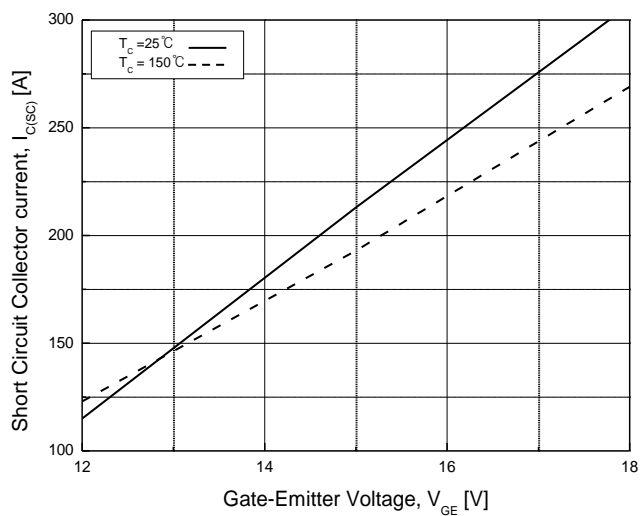
**Fig.2 Typical Collector-Emitter Saturation Voltage**



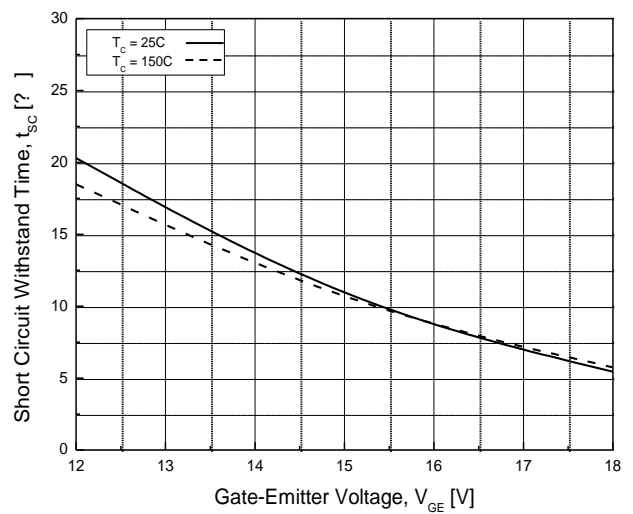
**Fig.3 Typical Transfer Characteristics**



**Fig.4 Typical Collector-Emitter Saturation Voltage at Case Temperature**



**Fig.5 Typical Short Circuit Collector Current**



**Fig.6 Typical Short Circuit Withstand Time**

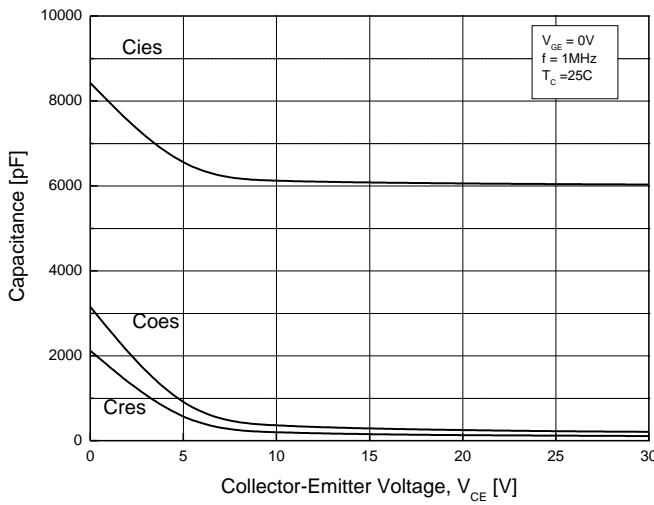


Fig.7 Typical Capacitance

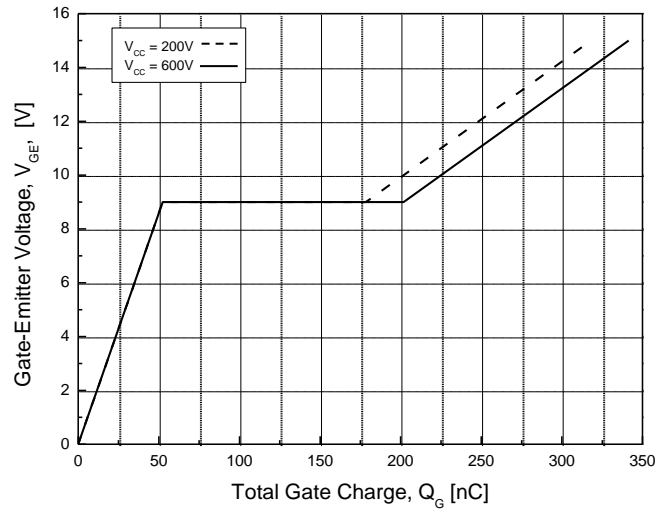


Fig.8 Typical Gate Charge

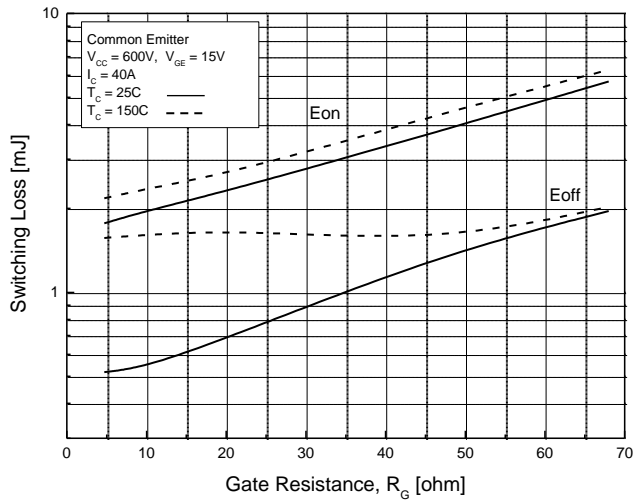


Fig.9 Switching Loss-Gate Resistance

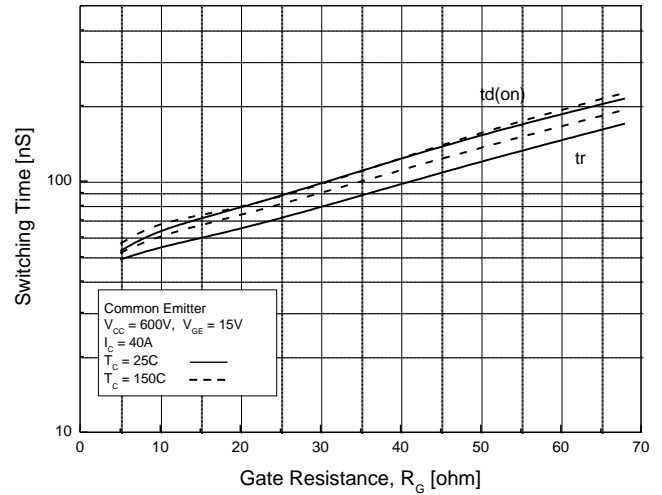


Fig.10 Turn on Characteristics-Gate Resistance

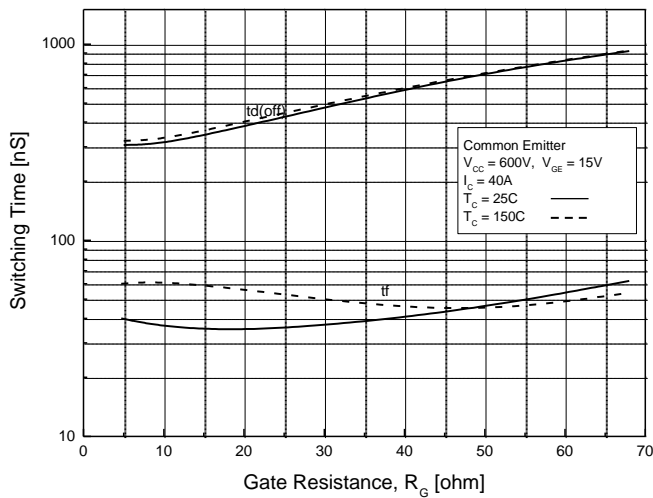


Fig.11 Turn off Characteristics-Gate Resistance

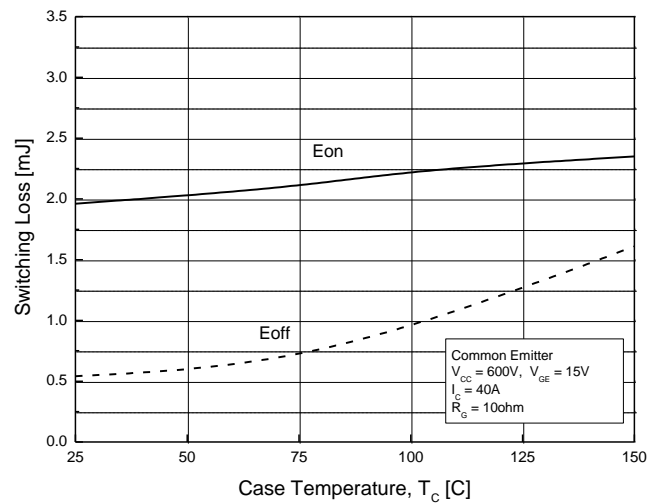
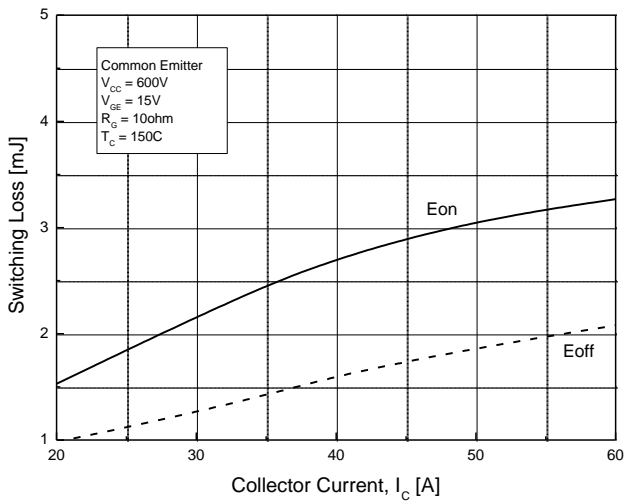
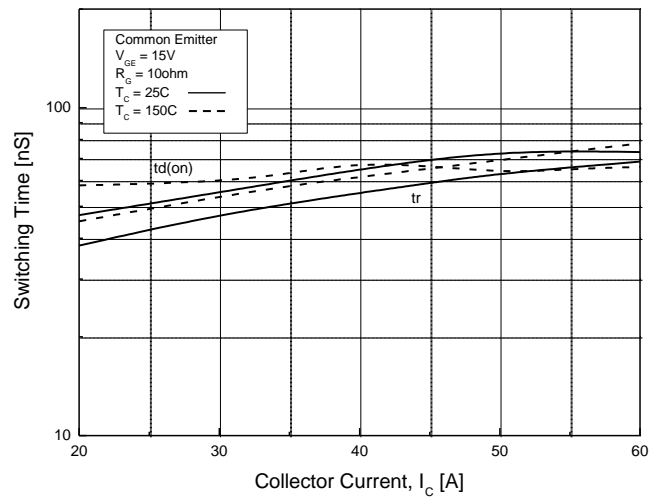


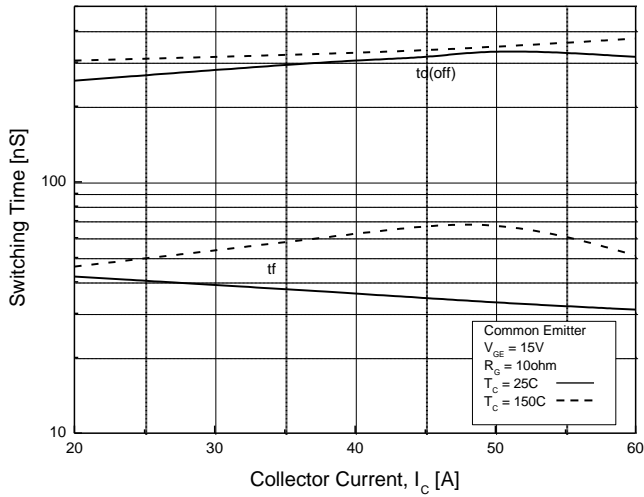
Fig.12 Switching Loss-Case Temperature



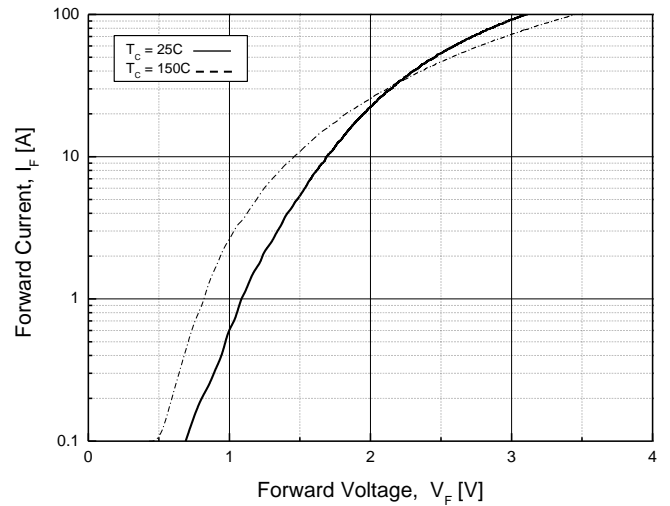
**Fig.13 Switching Loss-Collector Current**



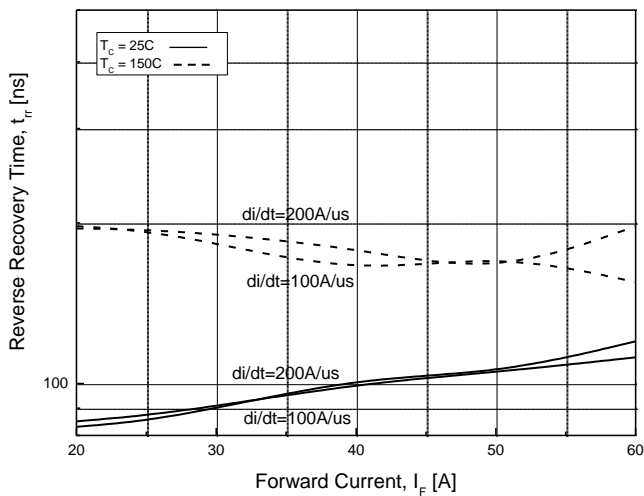
**Fig.14 Typical Turn on-Collector Current**



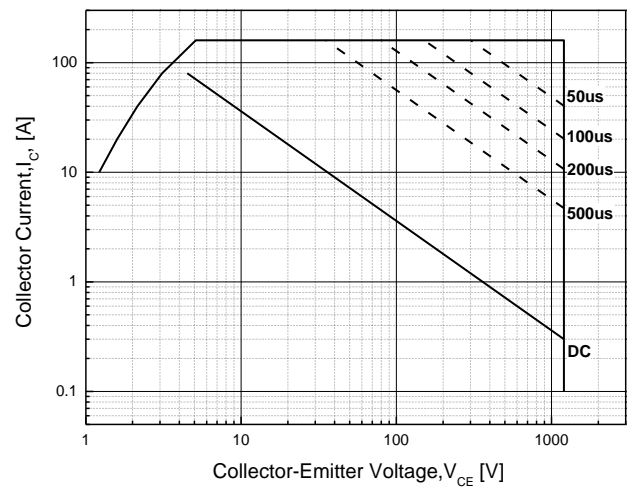
**Fig.15 Typical Turn off-Collector Current**



**Fig.16 Diode Forward Characteristics**



**Fig.17 Typical Turn off-Collector Current**



**Fig.18 Forward Bias Safe Operating Area**

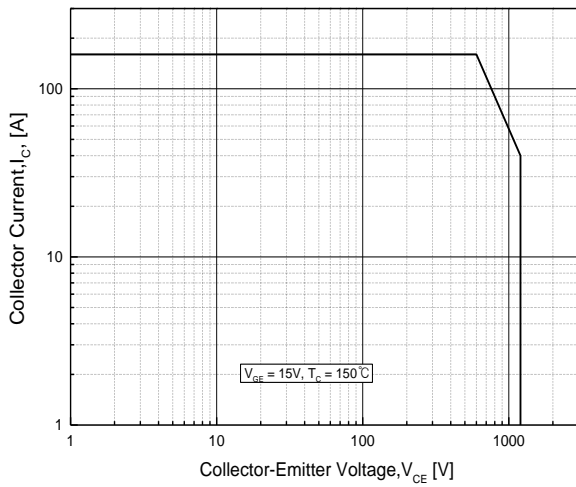


Fig.19 Reverse Bias Safe Operating Area

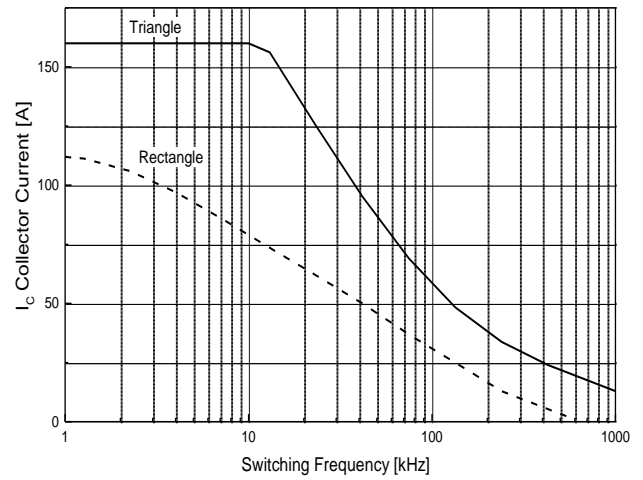


Fig.20 Switching frequency – Collector current

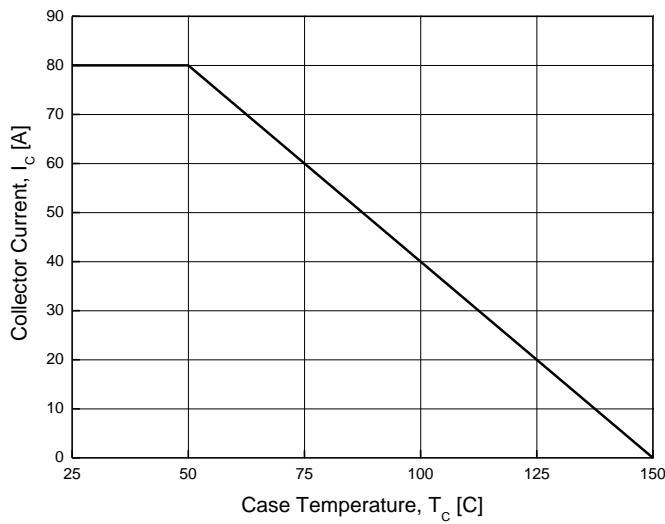


Fig.21 Case Temperature – Collector Current

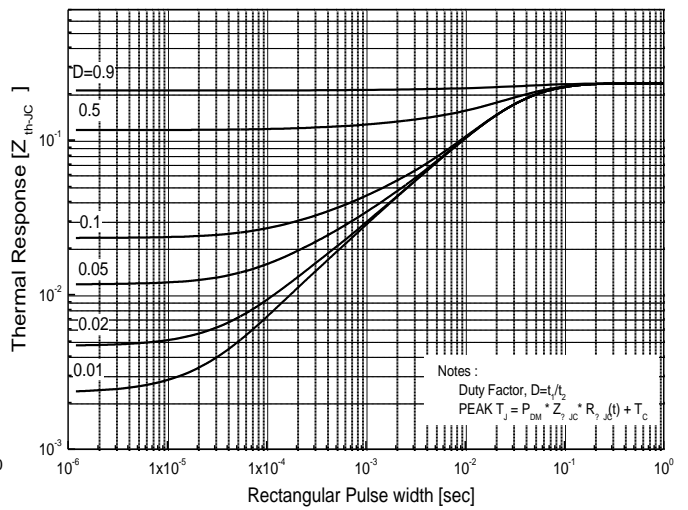
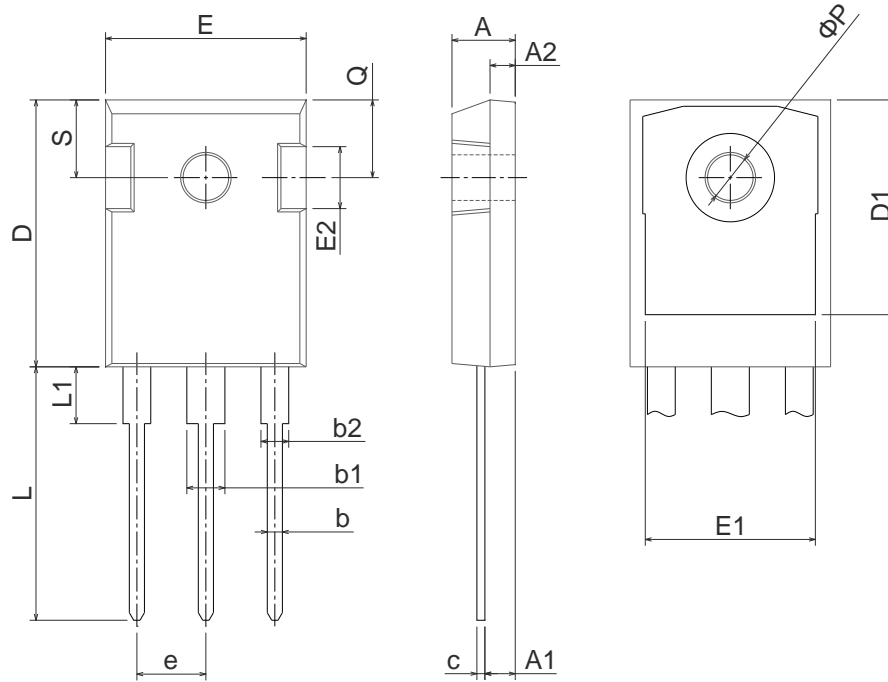


Fig.22 IGBT Transient Thermal Impedance

# Physical Dimension

## TO-247

Dimensions are in millimeters, unless otherwise specified



Dimension	Min(mm)	Max(mm)
A	4.70	5.31
A1	2.20	2.60
A2	1.50	2.49
b	0.99	1.40
b1	2.59	3.43
b2	1.65	2.39
c	0.38	0.89
D	20.30	21.46
D1	13.08	-
E	15.45	16.26
E1	13.06	14.02
E2	4.32	5.49
e	5.45BSC	
L	19.81	20.57
L1	-	4.50
ΦP	3.50	3.70
Q	5.38	6.20
S	6.15BSC	

**DISCLAIMER:**

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